٢	1 2	3 4	5		6		
	har-flex <sup>®</sup> THR angled male connector			RECOMMENDATION FOR SOLDER PROCESSING			
	harting har-flex THR angled male connection	So	Solder paste recommendation				
		Th	The har-flex connectors are solderable with established lead-f				
I	GENERAL INFORMATION	PC	PCB pad plating				
Γ	No. of contacts	from 6 to 100poles, all even numbers	Th	The har-flex connectors are solderable on lead-free pad surface   Stencil recommendation   The solder deposition has to be placed on the pad area of the Ideally, the solder deposition has the same length-to-width rat The size of the solder stencil apertures is depending on the th In general, a thinner stencils will need larger apertures to result The minimum required solder paste volume for the signal pins For example, this can be achieved with the following stencil data			
	Contact spacing	1,27mm x 1,27mm [0,050"x0,050"]	Ste				
	Test Voltage	500V					
	Contact resistance	< 25 mOhm	Ide				
	Insulation resistance	≥ 10x10^9Ω					
	Working current acc. to IEC 60512, at 70°C, 80% derating	see derating diagram					
	Working temperature range	-55°C +125°C					
	Termination technology	SMT					
	Reflow processing temperature	min. 150s >217°C		Stencil thickness	PCB pad size	proposal ster	
	(acc. to ECA/IPC/JEDEC J-STD-075 Level PSL R0)	min. 30s > 240°C		150 µm	0,8 x 0,8 mm	0,72 x	
	Clearance & creepage distance	0,4mm min.		•			
	Insertion force (depending on mating connector)	approximately 0,5N/contact				Ho	
	Withdrawal force (depending on mating connector)	approximately 0,5N/contact		Stencil thickness	PCB pad size	proposal ster	
	Mating cycles	PL1 : 500 mating cycles		150 µm	Ø0,8 mm	Ģ	
		PL2 : 250 mating cycles		stencil with lower thickn			
	RoHS - compliant	Yes		ncil aperture. Depending			
		Yes		sealing during solder paste printing and to reduce the clean than the PCB pad about 10% or 25µm encircling.			
	Working voltage acc. to to IEC 60664-1	100V / 150V (depending on installation category) ECBT2.E102079		Coplanarity of contacts			
	UL file acc. UL 1977		Cop				
	UL file acc. CSA-C22.2 (for Canada)	ECBT8.E102079	All (	connectors are tested fo	<sup>-</sup> coplanarity of con	tacts and are in	
	MSL level acc. ECA/IPC/JEDEC J-STD-075	PSL R0 MSL 1					
Ļ	INSULATOR MATERIAL						
	Material	LCP (liquid crystalline polymer)	Per	formance level			
	Color	Black	Per	Performance level 1 (recommended for majority of applications) Initial 250 mating cycles, 10 days gas test (25°C / 75% r.h.) usi Measurement of contact resistance. The remaining 250 mating and visual inspection. Visual inspection. No abrasion of the contact finish through to the			
	UL classification	UL94-V0					
	Material group acc. IEC 60664-1	IIIa (175≤CTI< 400)					
r	CONTACT MATERIAL		Visu				
ł			Par	t number definition : 15	2		
	Contact material	Copper alloy	Por	formance level 2			
	Plating termination zone	Sn		al 125 mating cycles, 4 of	lays gas test (25°C	; / 75% r.h.) usin	
	Plating contact sliding side	Au over PdNi (acc. to Performance level)	Mea	asurement of contact res			
	DERATING DIAGRAM acc. to IEC 60512-5 (Current carrying capacity)			visual inspection. Jal inspection. No abrasi	on of the contact fi	nich through to t	
		- Neder Sol - 10ed		t number definition : 15			
	The current carrying capacity is limited by maximum	4 <b>A</b>					
	temperature of materials for inserts and contacts including			Performance level S4 Defined contact surface of min. 0,06 µm Au over 0,7+0,2µm Pdl			
	terminals. The current capacity curve is valid for continuous, non			t number definition : 15			
	interrupted current loaded contacts of connectors when			All Dimensions in I		size tol.	
	simultaneous power on all contacts is given, without	Electrical load [A]		Original Size DIN #	.3 1:1		
	exceeding the maximum temperature.			All rights reserved	d Created by ZHUANGJ	Inspected by	
	Control and test procedures according to DIN IEC 60512-5		HARTING	Department EL PD		LUOK	
		0 10 20 30 40 50 60 70 80 90 100 110 120 130			Title har_flex	THR male angle	
		0 10 20 30 40 50 60 70 80 90 100 110 120 130					
	derating curve at Imax*0,8 (IEC 60512-5-2)	či 10 20 30 40 50 60 70 80 90 100 110 120 130 Temperature [°C]	HARTI	ING Electronics GmbH			
				ING Electronics GmbH 139 Espelkamp		Number 1515121(	

	7			8		1				
ad-free SAC / SnNi solder but also leaded solder e.g. SnPb40										
urfaces	like HAL, NiAu, Ir	nmer	sion Sn.							
f the contact solder tines. h ratio and center point like the PCB pads. he thickness of the stencil. result in the required volume of solder paste. pins is 0,078mm <sup>3</sup> , for the hold down it is 1,179mm <sup>3</sup> . cil data : Signal pins stencil aperture size Calculated solder paste volume 72 x 0,72 mm 0,078 mm <sup>3</sup>										
Hold-d	owns									
stencil a	aperture size	calc	ulated solder	paste	volume					
Ø2,3			1,179	•						
e the minimum required solder paste volume by enlarging the depostion may protrude the PCB pads. But to achieve a good ning interval of the stencil, the aperture should be smaller										
e in the range of 6 pin to 50 pin: ≤ 0,1mm 52 pin to 68 pin: ≤ 0,12mm										
			pin: ≤ 0,13n							
	-		0 pin: <b>≤</b> 0,15							
						D				
ions) ) using H2S 10 ppb, NO2 200 ppb, CL2 10 ppb, SO2 200 ppb. ting cycles are subject to measurement of contact resistance										
to the b	oase material. No	func	tional impairi	nent.						
using H2S 10 ppb, NO2 200 ppb, CL2 10 ppb, SO2 200 ppb. ting cycles are subject to measurement of contact resistance to the base material. No functional impairment.										
n PdNi										
		Ref.								
y	Standardisation	Sub. Date State								
J	HOFFMANN		-07-29	Final Re	elease					
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